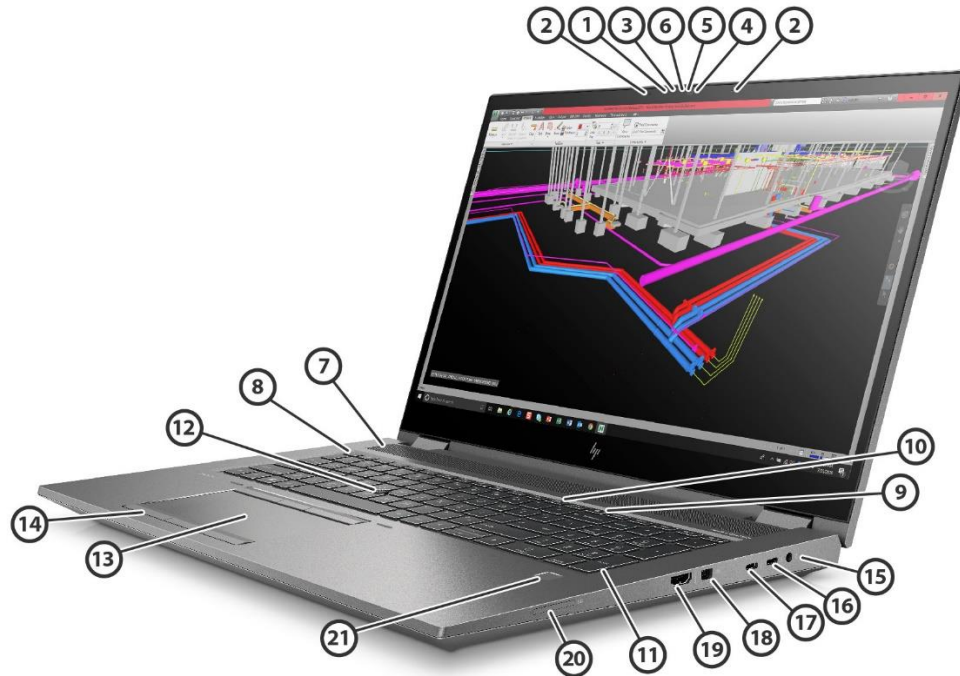


Overview

HP ZBook Fury 17 G7 Mobile Workstation

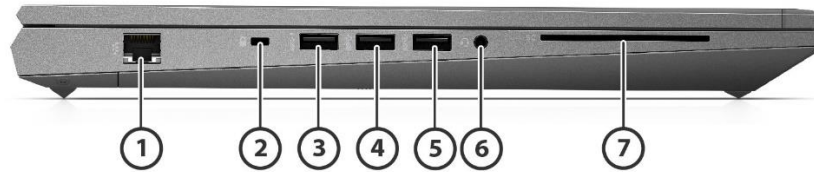


1. Ambient Light Sensor
2. Internal Microphones (optional)
3. Camera LEDs (optional)
4. Camera (optional)
5. IR Camera (optional)
6. Camera Cover (optional)
7. Speakers with Discrete Amplifier
8. Function Keys (changes with configured options)
9. Power button
10. HP Programmable Key
11. Numeric Keypad
12. Pointstick

Right

13. Touchpad
14. 3-button Touchpad
15. Indicator LEDs: Power light, Wireless light, Storage usage light
Power connector
16. USB Type-C® with Thunderbolt™
17. USB Type-C® with Thunderbolt™
18. Mini DisplayPort™
19. HDMI port
20. SD Card Reader
21. Fingerprint Sensor (optional)

Overview



Left

1. RJ-45
2. Nano security lock slot
3. USB 3.1 Gen 1 Charging Port
4. USB 3.1 Gen 1
5. USB 3.1 Gen 1
6. Audio Combo Jack
7. Smart Card Reader

Overview

At A Glance

- Work anywhere without compromising on performance or security with Windows 10 Pro ¹, powered by HP's collaboration and connectivity technology.
- Accelerate your workflow. Power through projects with up to 128 GB RAM ² for fast rendering, editing and visual effects performance.
- Take multitasking to the next level with the Intel® Core™ i9 processor ³ designed to handle complex, multithreaded apps like Adobe® Premier Pro, and with fast clock speeds you can boost your speed on single threaded apps like Autodesk 3ds Max.⁴
- Run demanding professional apps with the newest generation Intel® Xeon® processors ⁵ for powerful performance and productivity.
- Experience high-end visualization and seamlessly render your biggest projects with the next generation NVIDIA® Turing architecture with Quadro® T-Series and RTX graphics¹⁹; Certified and supported for the apps you use every day.
- Strenuously tested to meet software certification and deliver superb performance with leading software providers, including Autodesk and Adobe® ⁶.
- Blitz through multiple tasks and ditch external drives with up to 10 TB ^{7,8}, local PCIe NVMe storage - up to 21x faster than standard HDD and 6x faster than SATA SSD ⁹.
- Have confidence with the HP's most secure mobile workstations. Instantly protect against visual hacking with HP Sure View ¹⁰, and defend against firmware and malware attacks with HP Sure Start ¹¹ and HP Sure Sense ¹², and have peace of mind with multi-factor authentication- including an infrared camera and fingerprint scanner ¹³.
- Enhanced transfer and upload speeds via dual Thunderbolt™ 3 ports. Get wide-ranging connectivity options to ensure maximum device interaction: USB 3.0, HDMI, mDP, SD card, Smart Card Reader and more.
- Designed for ultimate durability, this ZBook undergoes brutal MIL-STD 810H ¹⁴ tests to help ensure this PC keeps rolling through your workday.
- Plug in to greater connectivity at your desktop with the HP Thunderbolt Dock for lightning-fast Thunderbolt™ 3 ¹⁵ transfers and the flexibility to run up to two external 4K displays ^{16,17}.
- Improve connectivity while on Wi-Fi® with HP Extended Range Wireless LAN that allows greater distance from transmission point and fast data throughput at shorter ranges ¹⁸.

¹ Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See <http://www.windows.com>.

² Up to 128GB nECC memory is an optional, configurable feature.

³ Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

⁴ Adobe Premier Pro and Autodesk 3ds Max sold separately.

⁵ Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

⁶ Adobe and Autodesk software sold separately.

⁷ For hard drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 3GB (for Windows 10) of system disk is reserved for system recovery software.

⁸ 8TB available at launch, 10TB planned to be available Spring, 2021.

⁹ Speeds based on 10TB PCIe NVMe storage.

¹⁰ Based on HP's unique and comprehensive security capabilities at no additional cost among desktop workstation vendors as of Sept. 2017 on HP Mobile Workstations with 7th Gen and higher Intel® Processors.

¹¹ HP Sure Start Gen5 is available on select HP PCs with Intel processors. See product specifications for availability.

¹² HP Sure Sense requires Windows 10. See product specifications for availability.

¹³ Infrared camera and fingerprint scanner are optional, configurable features.

¹⁴ Testing is not intended to demonstrate fitness of U.S. Department of Defense (DoD) contract requirements or for military use. Test results are not a guarantee of future performance under these test conditions. Accidental damage requires an optional HP Accidental Damage Protection Care Pack.

Overview

¹⁵ HP Thunderbolt Dock with Thunderbolt™ 3 sold separately.

¹⁶ External displays sold separately.

¹⁷ Optional hybrid graphics is required to run up to two external 4K displays.

¹⁸ Based on internal testing vs. previous generation product with 802.11ac wireless LAN module.

¹⁹ The HP custom vapor chamber (Z VaporForce) is only available on configurations with NVIDIA RTX graphics or AMD Radeon graphics

NOTE: See important legal disclosures for all listed specs in their respective features sections.

Features

OPERATING SYSTEM

Preinstalled OS	Windows® 10 Pro 64 - HP recommends Windows® 10 Pro for business. ¹ Windows® 10 Pro for Workstations 64 ¹ Windows® 10 Home 64 ¹ Windows® 10 Home Single Language 64 ¹ FreeDOS 3.0
Web support OS	Red Hat® Enterprise Linux® 8 ² Ubuntu Linux 18.04 ² Windows® 10 Enterprise 64 ¹
Supported Version	HP tested Windows® 10, version 1809 on this platform. For testing information on newer versions of Windows® 10, please see: https://support.hp.com/document/c05195282 .

¹ Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See <http://www.windows.com>.

² For detailed Linux® OS/hardware support information, see: http://www.hp.com/linux_hardware_matrix

PROCESSOR

10th Generation Intel® Xeon® W-10885M vPro™ with Intel® UHD Graphics (2.4 GHz base frequency, up to 5.3 GHz with Intel® Turbo Boost Technology, 16 MB cache, 8 cores)^{1,2,3,4,5,6}

10th Generation Intel® Core™ i9-10885H vPro™ with Intel® UHD Graphics (2.4 GHz base frequency, up to 5.3 GHz with Intel® Turbo Boost Technology, 16 MB cache, 8 cores)^{1,2,3,4,5,6}

10th Generation Intel® Core™ i7-10850H vPro™ with Intel® UHD Graphics (2.7 GHz base frequency, up to 5.1 GHz with Intel® Turbo Boost Technology, 12 MB cache, 6 cores)^{1,2,3,4,5,6}

10th Generation Intel® Core™ i7 10750H with Intel® UHD Graphics (2.6 GHz base frequency, up to 5.0 GHz with Intel® Turbo Boost Technology, 12 MB cache, 6 cores)^{1,2,3,4,5}

10th Generation Intel® Core™ i5-10400H vPro™ with Intel® UHD Graphics (2.6 GHz base frequency, up to 4.6 GHz with Intel® Turbo Boost Technology, 8 MB cache, 4 cores)^{1,2,3,4,5,6}

10th Generation Intel® Core™ i5 10300H with Intel® UHD Graphics (2.5 GHz base frequency, up to 4.5 GHz with Intel® Turbo Boost Technology, 8 MB cache, 4 cores)^{1,2,3,4,5}

¹ Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

² Processor speed denotes maximum performance mode; processors will run at lower speeds in battery optimization mode.

³ Intel® Turbo Boost performance varies depending on hardware, software and overall system configuration. Energy Efficient Turbo is a power management feature that can lower the maximum core ratio (frequency), if the CPU thinks it can achieve about the same performance as with the maximum turbo frequency. Energy Efficient Turbo feature is disabled in Comet Lake H in order to prioritize performance in DC mode. It can be changed in F10 BIOS settings. See www.intel.com/technology/turboboost for more information.

⁴ In accordance with Microsoft's support policy, HP does not support the Windows 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows 8 or Windows 7 drivers on <http://www.support.hp.com>.

⁵ For full Intel® vPro® functionality, Windows, a vPro supported processor, vPro enabled Q370 chipset or higher and vPro enabled WLAN card are required. Some functionality, such as Intel Active management technology and Intel Virtualization technology, requires additional 3rd party software in order to run. Availability of future "virtual appliances" applications for

Features

Intel vPro technology is dependent on 3rd party software providers. Compatibility of this generation of Intel vPro technology-based hardware with future "virtual appliances" is yet to be determined.

Features

CHIPSET

Mobile Intel® WM 490

INTEL® CORE™ I5 WITH VPRO/CORE I7 WITH VPRO/XEON® WITH VPRO TECHNOLOGY CAPABLE

Intel® Core™ i5 with vPro™, Core™ i7 with vPro™, Core™ i9 with vPro™ and Xeon® with vPro™ technology is a selectable feature that is available on units configured with select processors, a qualified Intel® WLAN module and a preinstalled Windows® operating system. It provides advances in remote manageability, security, energy efficient performance, and wireless connectivity. Intel® Active Management Technology (iAMT) offers built-in manageability and proactive security for networked mobile workstations, even when they are powered off* or when the operating system is inoperable. It can help identify threats before they reach the network, isolate infected systems, and update regardless of their power state. ^{1,2}

¹ Requires a Windows operating system, network hardware and software, connection with a power source, and a direct (non-VPN) corporate network connection which is either cable or wireless LAN.

² Some functionality of Intel® Core™ i5 with vPro™/Core™ i7 with vPro™/Core™ i9 with vPro™/Xeon® with vPro™ technology, such as Intel® Active Management technology and Intel® Virtualization technology, requires additional third-party software in order to run. Availability of future "virtual appliances" applications for Intel® Core™ i5 with vPro™/Core™ i7 with vPro™/Core™ i9 with vPro™/XEON® with vPro™ technology is dependent on third-party software providers. Compatibility with future "virtual appliances" is yet to be determined.

GRAPHICS

Integrated

Intel® UHD Graphics 630 ^{1,2,3,4,5}

Discrete

NVIDIA Graphic options:

NVIDIA® Quadro® RTX 5000 with Max-Q Design (16 GB GDDR6 dedicated) ^{1,2,3,4,5,7}

NVIDIA® Quadro® RTX 4000 with Max-Q Design (8 GB GDDR6 dedicated) ^{1,2,3,4,5,7}

NVIDIA® Quadro® RTX 3000 (6 GB GDDR6 dedicated) ^{1,2,3,4,5,7}

NVIDIA® Quadro® T2000 with Max-Q Design (4 GB GDDR6 dedicated) ^{1,2,3,4,5}

NVIDIA® Quadro® T1000 with Max-Q Design (4 GB GDDR6 dedicated) ^{1,2,3,4,5}

AMD Graphic options:

AMD Radeon Pro W5500M (4 GB GDDR6 dedicated) ^{1,2,3,4,5,7}

AMD Radeon RX 5500M (4 GB GDDR6 dedicated) ^{1,2,3,4,5,7}

¹ UHD content required to view UHD images.

² Support HD decode, DX11, DX12, HDMI 1.4, HDCP 2.3 via DP up to 4K @ 60Hz and via HDMI up to 4K @ 30Hz

³ HDMI cable Sold Separately

⁴ Shared video memory (UMA) uses part of the total system memory for video performance. System memory dedicated to video performance is not available for other use by other programs.

⁵ miniDP cable sold separately.

⁶ GPU configurations may be limited to specific panel options

⁷ The HP custom vapor chamber (Z VaporForce) is only available on configurations with NVIDIA RTX graphics or AMD Radeon graphics

Features

DISPLAY

Non-touch

- 17.3" diagonal FHD (1920 x 1080) IPS eDP anti-glare WLED-backlit and ambient light sensor 300 nits 72% CG^{1,2}
- 17.3" diagonal UHD (3840 x 2160) IPS eDP1.4 + PSR2 anti-glare WLED-backlit and ambient light sensor 550 nits 100% DCI-P3^{1,2,3,4}
- 17.3" diagonal UHD (3840 x 2160) IPS HDR 400 eDP1.4 + PSR2 anti-glare WLED-backlit and ambient light sensor 550 nits 100% DCI-P3 Next Gen HP Dream Color display^{1,2,3,4}

Touch

- 17.3" diagonal UHD (3840 x 2160) IPS HDR 400 eDP1.4 + PSR2 WLED-backlit touch screen with Corning® Gorilla® Glass 5 and ambient light sensor 550 nits 100% DCI-P3^{1,2,3,4}

HP Virtual Reality Headset (sold separately)

- HP Reverb
- HP Reverb G2

¹ UHD content required to view UHD images.

² Resolutions are dependent upon monitor capability, and resolution and color depth settings.

³ Display options may be limited to specific GPU Configurations.

⁴ VESA DisplayHDR 400 certifications are pending.

⁵ Virtual Reality content is required to view Virtual Reality images

Features

STORAGE AND DRIVES*

Max Storage

10TB through four M.2 NVMe drives¹

8TB through two M.2 NVMe drives and one 2.5" SATA drive¹

(up to 1) HDD Storage (SATA 3.2)²

500 GB 7200 rpm SATA FIPS 140-2 SED HDD

500 GB 7200 rpm SATA HDD

1 TB 7200 rpm SATA HDD

2 TB 5400 rpm SATA HDD

(up to 4) M.2 Storage (NVMe™ PCIe SSD)²

256 GB PCIe (NVMe™) TLC Self Encrypting (SED) Solid State Drive

512 GB PCIe (NVMe™) TLC Self Encrypting (SED) Solid State Drive

256 GB PCIe (NVMe™) TLC Solid State Drive

512 GB PCIe (NVMe™) TLC Solid State Drive

1 TB PCIe (NVMe™) TLC Solid State Drive³

2 TB PCIe (NVMe™) TLC Solid State Drive³

4 TB PCIe (NVMe™) TLC Solid State Drive¹

¹4TB PCIe Gen 3 x4 NVMe M.2 SSD TLC Option will be available by Spring 2021. 4TB can only be assigned to storage slot 2.

²Storage slot 1-4 can support NVMe protocol

³Storage slot 1, 3 and 4 can support SATA protocol

⁴Only storage slots 1-3 can support RAID

* For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35GB of disk is reserved for system recovery software.

DRIVE CONTROLLERS

M.2 Storage Bay (PCIe NVMe)

PCIe Gen 3 x4 lanes NVMe Solid State Drive

RAID:

RAID 0 and RAID 1 support¹

¹ Support only available with 1TB + 1TB M.2 storage or 2TB + 2TB M.2 storage combinations

MEMORY

Maximum Memory^{3,2,5}

128 GB DDR4-2667 non-ECC SDRAM

64 GB DDR4-2667 ECC SDRAM

4 DDR4 SODIMMS⁴

Supports Dual Channel Memory¹

Slots are customer accessible / upgradeable

¹Maximized dual-channel performance requires SODIMMs of the same size and speed in both memory channels.

² Due to the non-industry standard nature of some third-party memory modules, we recommend HP branded memory to ensure compatibility. If you mix memory speeds, the system will perform at the lower memory speed.

³Transfer rates up to 2667 MT/s for nECC and ECC memory combinations when memory suppliers are consistent. If suppliers are not consistent, speeds may drop to 2133 MT/s for nECC and 2400 MT/s for ECC memory combinations. A custom configuration including part number AY104AV can be used to lock in a consistent vendor.

⁴ Intel® allows architectures designed with four DIMM slots to run at 2400 MT/s

⁵ Maximum memory capacities assume Windows 64-bit operating systems. With Windows 32-bit operating systems, memory above 3 GB may not all be available due to system resource requirements.

Features

Features

NETWORKING/COMMUNICATIONS

LAN

Intel® I219-LM GbE, vPro™¹
Intel® I219-V GbE, non-vPro™¹

¹GbE - The term "10/100/1000" or "Gigabit" Ethernet indicates compatibility with IEEE standard 802.3ab for Gigabit Ethernet, and does not connote actual operating speed of 1 Gb/s. For high-speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.

WLAN

Intel® Wi-Fi 6 AX201 (2x2) and Bluetooth® 5 combo, vPro™¹
Intel® Wi-Fi 6 AX201 (2x2) and Bluetooth® 5 combo, non-vPro™¹

¹Wireless cards are optional or add-on features and requires separately purchased wireless access point and internet service. Availability of public wireless access points limited. The specifications for the 802.11ac WLAN are draft specifications and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ac WLAN devices.

WWAN¹

Intel® XMM™ 7360 LTE Advanced CAT 9

¹ WWAN use requires separately purchased service contract. Check with service provider for coverage and availability in your area. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products, and in all regions.

Optional Near Field Communication (NFC) module

AUDIO/MULTIMEDIA

Audio

Audio by Bang & Olufsen, dual stereo speakers, HP World Facing Microphone dual array digital microphone¹, functions keys for volume up and down, combo microphone/headphone jack, HD audio

¹Dual-microphone array when equipped with optional webcam and optional world facing microphone.

Camera^{1,2,3}

720p HD webcam with IR
720p HD webcam

¹ FHD and HD content required to view HD images respectively.

² Windows Hello face authentication utilizes a camera specially configured for near infrared (IR) imaging to authenticate and unlock Windows devices as well as unlock your Microsoft Passport.

³Camera-configured options come with a Privacy Shutter

Features

KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS

Keyboard

HP Premium Quiet Keyboard, full-size, spill-resistant, backlit, a Programmable Key, with sperate numeric keypad, HP DuraKey, touchpad with glass surface, multi-touch gestures and taps enabled

Pointing Devices

Dual pointstick; Touchpad with multi-touch gestures enabled, taps enabled as default; Microsoft Precision Touchpad Default Gestures Support

SOFTWARE AND SECURITY

Workstation ISV Certifications

See the latest list of certifications at: <http://www.hp.com/go/isv>

HP ZCENTRAL REMOTE BOOST SOFTWARE

The remote desktop solution for serious workstation users and their most demanding applications. Download at: <http://www.hp.com/go/RGS>

HP Performance Advisor

HP Performance Advisor enables optimal configuration of HP Mobile Workstations delivering stability and best performance. HP Performance Advisor will guide your system setup allowing a "custom" configuration that best matches the workstation to user requirements. Download at: <http://www.hp.com/go/performanceadvisor>

Software

Bing search for IE11

Buy Office

HP Hotkey Support

HP Image Assistant

HP Noise Cancellation Software

HP Performance Advisor⁸

HP Sure Recover

HP ZCentral Remote Boost²

HP Support Assistant^{1,7}

Native Miracast support⁴

HP Connection Optimizer⁹

HP Cloud Recovery

myHP

Security Management

Absolute persistence module⁶

HP Admin

HP Device Access Manager

HP FingerPrint Sensor

HP Manageability Integration Kit Gen4¹¹

HP Power On Authentication

Security lock slot¹²

Trusted Platform Module TPM 2.0 Embedded Security Chip with Windows 10 (Common Criteria EAL4+ Certified)(FIPS 140-2 Level 2 Certified)

Master Boot Record security

Pre-boot authentication

Windows Defender¹⁰

HP Client Security Manager Gen5¹⁶

HP BIOSphere Gen6⁵

HP Sure Recover Gen3¹³

HP Sure Start Gen6^{5,14}

Features

HP Secure Erase¹⁵
HP Sure Sense¹⁷
HP Secure Platform¹⁸
HP Sure Click
HP Sure Run Gen3
HP Tamper Lock
Smartcard Reader - Alcor AU9560 (FIPS 201 Compliant)

For more information on HP Client Security Software Suite, refer to <http://www.hp.com/go/clientsecurity>.

¹ HP Support Assistant - Requires Windows and Internet Access.

² HP Z Central Remote Boost Software does not come preinstalled on Z Workstations but can be downloaded and run on all Z desktop and laptops without license purchase. With non-Z sender devices, purchase of perpetual individual license or perpetual floating license per simultaneously executing versions and purchase of ZCentral Remote Boost Software Support is required. RGS requires Windows, RHEL (7 or 8), UBUNTU 18.04 LTS, or HP ThinPro 7 operating systems. MacOS (10.13 or newer) operating system is only supported on the receiver side. Requires network access. The software is available for download at hp.com/ZCentralRemoteBoost.

⁴ Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming media players that also support Miracast. You can use Miracast to share what you're doing on your PC and present a slide show. For more information: <http://windows.microsoft.com/en-us/windows-8/project-wireless-screen-miracast>.

⁵ HP BIOSphere Gen6 is available on select HP Pro, Elite and ZBook PCs. See product specifications for details. Features may vary depending on the platform and configurations.

⁶ Absolute agent is shipped turned off, and will be activated when customers activate a purchased subscription. Subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. The Absolute Recovery Guarantee is a limited warranty. Certain conditions apply. For full details visit:

<http://www.absolute.com/company/legal/agreements/computrace-agreement>. Data Delete is an optional service provided by Absolute Software. If utilized, the Recovery Guarantee is null and void. In order to use the Data Delete service, customers must first sign a Pre-Authorization Agreement and either obtain a PIN or purchase one or more RSA SecurID tokens from Absolute Software.

⁸ HP Performance Advisor Software - HP Performance Advisor is ready and waiting to help you get the most out of your HP Workstation from day one—and every day after. Learn more or download at: <https://www8.hp.com/us/en/workstations/performance-advisor.html>

⁹ HP Connection Optimizer requires Windows 10.

¹⁰ Microsoft Defender Opt in and internet connection required for updates.

¹¹ HP Manageability Integration Kit can be downloaded from <http://www.hp.com/go/clientmanagement>.

¹² Nano Security lock slot is Lock sold separately.

¹³ HP Sure Recover Gen3: See product specifications for availability. Requires an open, wired network connection. You must back up important files, data, photos, videos, etc. before using HP Sure Recover to avoid loss of data. HP Sure Recover (Gen1) does not support platforms with Intel® Optane™.

¹⁴ HP Sure Start Gen6 is available on select HP PCs with Intel processors. See product specifications for availability.

¹⁵ For the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method. HP Secure Erase does not support platforms with Intel® Optane™.

¹⁶ HP Client Security Manager Gen5 requires Windows and is available on select HP Pro, Elite and ZBook PCs. See product specifications for details.

¹⁷ HP Sure Sense requires Windows 10. See product specifications for availability.

¹⁸ Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited.

Features

POWER

Power Supply

Up to 15 hours 45 minutes¹

HP Long Life 8-cell, 94 Wh Li-ion polymer²

120 W Slim Smart external AC power adapter

150 W Slim Smart external AC power adapter

200 W UltraSlim Smart external AC power adapter

120 W power adapter is configurable with Intel UMA graphics

150 W power adapter is configurable with NVIDIA Quadro T1000 and T2000 configurations

200 W power adapter is configurable with NVIDIA Quadro RTX 3000³ or higher configurations

¹ Measured with MobileMark 14

² Batteries have a default one year limited warranty except for Long Life batteries which will have same 1-year or 3-year.

³ The HP custom vapor chamber (Z VaporForce) is only available on configurations with NVIDIA RTX graphics or AMD Radeon graphics

ENVIRONMENTAL

ENERGY STAR® certified and EPEAT® 2.0 registered where applicable. EPEAT® registration varies by country. See www.epeat.net for registration status by country.¹

Low halogen²

¹ Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. Status varies by country. Visit www.epeat.net for more information.

² External power supplies, power cords, cables and peripherals are not low halogen. Service parts obtained after purchase may not be low halogen.

Features

WEIGHTS & DIMENSIONS

Dimensions (w x d x h)

39.84 x 26.71 x 2.69 cm

15.69 x 10.52 x 1.06 in

Weights

Starting at 2.76kg (6.08 lb)

Weight varies by configuration and components.

A deck: Anodized Aluminum

B deck: Aluminum with plastic antenna cover; Touch has Corning® Gorilla® Glass 5

C deck: Anodized Aluminum

D deck: Magnesium Die Cast

E door: Magnesium Die Cast

Metal Alloy Hinges

PORTS/SLOTS

1 smart card reader

1 SD 4.0 Media Card Reader

Left side⁶

1 RJ-45

1 USB 3.1 Gen 1 (charging)

2 USB 3.1 Gen 1

1 headphone/microphone combo

Right side⁶

1 power connector

2 USB Type-C® (Thunderbolt™ 3, pass through support DisplayPort™ 1.4², USB 3.1 Gen 2, with BC 1.2)

1 Mini DisplayPort™ 1.4

1 HDMI 2.0b^{1,3,4,5}

¹ HDMI port-cable not included.

² Mini DisplayPort™ 1.4 with discrete, 1.2 with UMA.

³ HDMI 2.0b with discrete, 1.4 with UMA.

⁴ When both USB Type-C® are in use, HDMI cannot be detected

⁵ When one USB Type-C® is in use, HDMI can be detected if USB Type-C® in use is assigned to different channel

⁶ When product is under heavy power loading, performance may be reduced to prevent battery drain. Disconnecting USB devices will restore system performance

SERVICE AND SUPPORT

HP Services offers 3-year and 1-year limited warranties and 90 day software limited warranty options depending on country. Batteries have a default one year limited warranty except for Long Life batteries which will have same 1-year or 3-year limited warranty as the platform. Refer to <http://www.hp.com/support/batterywarranty/> for additional battery information. On-site service and extended coverage is also available. HP Care Pack Services are optional extended service contracts that go beyond the standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: <http://www.hp.com/go/cpc>.

¹Sold separately or as an optional feature. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. HP services are

Features

governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product. Consult your local HP Customer Support Center for details.

Technical Specifications – System Unit

SYSTEM UNIT

Stand-Alone Power Requirements (AC Power)	Nominal Operating Voltage	19.5V	
	Average Operating Power(idle)	System in idle mode + max panel brightness	Adapter Safety test condition
Temperature	Discrete Graphics	80W	
	Max Operating Power	<200W	
Relative Humidity	Operating	41° to 122° F (5° to 50° C) (reading optical) 41° to 113° F (5° to 45° C) (writing optical)	
	Non-operating	-40° to 140° F (-40° to 60° C)	
Shock	Operating	40 G, 2 ms, half-sine	
	Non-operating	200 G, 2 ms, half-sine	
Random Vibration	Operating	0.75 grms	
	Non-operating	1.50 grms	
Maximum Altitude (unpressurized)	Operating	-50 to 10,000 ft. (-15.24 to 3,048 m)	
	Non-operating	-50 to 15,000 ft. (-15.24 to 12,192 m)	
Planned Industry Standard Certifications	UL	Yes	
	CSA	Yes	
	FCC Compliance	Yes	
	ENERGY STAR®	Yes	
	EPEAT®	Yes	
	ICES	Yes	
	Australia / NZ A-Tick Compliance	Yes	
	CCC	Yes	
	Japan VCCI Compliance	Yes	
	KCC	Yes	
	BSMI	Yes	
	CE Marking Compliance	Yes	
	MIL STD 810H	Yes	
	BNCI or BELUS	Yes	
	GOST	Yes	
	Saudi Arabian Compliance (ICCP)	Yes	
UKRSERTCOMPUTER	Yes		

¹Configurations of the HP ZBook Fury 17 G7 that are ENERGY STAR® qualified are identified as HP ZBook Fury 17 G7 ENERGY STAR on HP websites and on <http://www.energystar.gov>.

² EPEAT® registered where applicable. EPEAT registration varies by country. See <http://www.epeat.net> for registration status by country. Search keyword generator on HP's 3rd party option store for solar generator accessories at www.hp.com/go/options.

Technical Specifications – Displays

DISPLAYS

17.3" diagonal FHD IPS eDP1.2 anti-glare WLED-backlit and ambient light sensor 300 nits 72% CG (1920 x 1080)	Outline Dimensions (W x H)	399.95 x 251.01 mm (max)		
	Active Area	381.89 x 214.81 mm		
	Weight	550 g (max)		
	Diagonal Size	17.3 inch		
	Thickness	4.0 mm (max)		
	Interface	eDP 1.2		
	Panel Technology	IPS		
	Surface Treatment	Anti-Glare		
	Touch Enabled	No		
	Refresh Rate	60 hrz		
	Brightness	300 nits		
	Pixel Resolution	Format	1920 x 1080 (FHD)	
		Configuration	RGB	
	Backlight	LED		
	PPI	127		
	Color Gamut Coverage	72% CG		
	Color Depth	6 bits + Hi FRC		
	Viewing Angle	UWVA 85/85/85/85		

All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

17.3" diagonal UHD IPS eDP1.4 + PSR2 anti-glare WLED-backlit and ambient light sensor 550 nits 100% DCI-P3 (3840 x 2160)	Outline Dimensions (W x H)	399.95 x 251.01 mm (max)		
	Active Area	381.89 x 214.81 mm		
	Weight	550 g (max)		
	Diagonal Size	17.3 inch		
	Thickness	4.0 mm (max)		
	Interface	eDP 1.4 + PSR2		
	Panel Technology	IPS		
	Surface Treatment	Anti-Glare		
	Touch Enabled	No		
	Refresh Rate	60 hrz		
	Brightness	550 nits		
	Pixel Resolution	Format	3840 x 2160 (UHD)	
		Configuration	RGB	
	Backlight	LED		
	PPI	127		
	Color Gamut Coverage	100% DCI-P3		
	Color Depth	6 bits + Hi FRC		
	Viewing Angle	UWVA 85/85/85/85		

All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

Technical Specifications – Displays

Next Gen HP Dream Color display 17.3" diagonal UHD IPS HDR 400 eDP1.4 + PSR2 anti-glare WLED-backlit and ambient light sensor 550 nits 100% DCI-P3 (3840 x 2160)	Outline Dimensions (W x H)	398.6 x 253 mm (max) (w/ bracket & PCB)		
	Active Area	382.12 x 214.94 mm		
	Weight	550 g (max)		
	Diagonal Size	17.3 inch		
	Thickness	4.0 mm (max)		
	Interface	eDP 1.4 + PSR2		
	Panel Technology	IPS		
	Surface Treatment	Anti-Glare		
	Touch Enabled	No		
	Contrast Ratio	1000:1 (typ.)		
	Refresh Rate	60Hz		
	Brightness	550 nits		
	Pixel Resolution	Pitch	3840 x 2160 (UHD)	
		Format	RGB	
	Backlight	LED		
	PPI	254		
	Color Gamut Coverage	100% DCI-P3		
	Color Depth	8 bits		
	Viewing Angle	UWVA 85/85/85/85		

All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

17.3" diagonal UHD IPS HDR 400 eDP1.4 + PSR2 WLED-backlit touch screen with Corning® Gorilla® Glass 5 and ambient light sensor 550 nits 100% DCI-P3 (3840 x 2160)	Outline Dimensions (W x H)	398.6 x 253 mm (max) (w/ bracket & PCB)		
	Active Area	382.12 x 214.94 mm		
	Weight	550 g (max)		
	Diagonal Size	17.3 inch		
	Thickness	4.0 mm (max)		
	Interface	eDP 1.4 + PSR2		
	Panel Technology	IPS		
	Surface Treatment	Gorilla Glass 5 with Anti-Glare		
	Touch Enabled	Yes		
	Contrast Ratio	1000:1 (typ.)		
	Refresh Rate	60Hz		
	Brightness	550 nits		
	Pixel Resolution	Pitch	3840 x 2160 (UHD)	
		Format	RGB	
	Backlight	LED		
	PPI	254		
	Color Gamut Coverage	100% DCI-P3		
	Color Depth	8 bits		
	Viewing Angle	UWVA 85/85/85/85		

All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

Technical Specifications – Storage

STORAGE AND DRIVES

256GB PCIe NVMe TLC M.2 2280 Solid State Drive	Form Factor	M.2 2280		
	Drive Weight	0.02 lb (10 g)		
	Capacity	256GB		
	Generation	1100		
	NAND Type	TLC		
	Height	2.6 mm Max		
	Width	0.87 in (22 mm)		
	Interface	ACS-3, SATA 3.2		
	Performance	Maximum Sequential Read	Maximum Sequential Write	
		3500 MB/s	2200 MB/s	
	Logical Blocks	1,000,215,216		
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]		
	Features	ATA Security; TCG Opal 2.0; FIPS DIPM; TRIM; DEVSLP		
	Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for system recovery software.			
256GB PCIe NVMe TLC M.2 2280 SED Opal 2 Solid State Drive	Form Factor	M.2 2280		
	Drive Weight	0.02 lb (10 g)		
	Capacity	256GB		
	Generation	1100		
	NAND Type	TLC		
	Height	2.6 mm Max		
	Width	0.87 in (22 mm)		
	Interface	ACS-3, SATA 3.2		
	Performance	Maximum Sequential Read	Maximum Sequential Write	
		3000 MB/s	1600 MB/s	
	Logical Blocks	1,000,215,216		
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]		
	Features	ATA Security; TCG Opal 2.0; FIPS DIPM; TRIM; DEVSLP		
	Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for system recovery software.			
512GB PCIe NVMe TLC M.2 2280 Solid State Drive	Form Factor	M.2 2280		
	Drive Weight	0.02 lb (10 g)		
	Capacity	512GB		
	Generation	1100		
	NAND Type	TLC		
	Height	2.6 mm Max		
	Width	0.87 in (22 mm)		
	Interface	ACS-3, SATA 3.2		
	Performance	Maximum Sequential Read	Maximum Sequential Write	
		3400 MB/s	2956 MB/s	

Technical Specifications – Storage

	Logical Blocks	1,000,215,216		
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]		
	Features	ATA Security; TCG Opal 2.0; FIPS DIPM; TRIM; DEVSLP		
		Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for system recovery software.		
512TB PCIe NVMe TLC M.2 2280 SED Opal 2 Solid State Drive	Form Factor	M.2 2280		
	Drive Weight	0.02 lb (10 g)		
	Capacity	512GB		
	Generation	1100		
	NAND Type	TLC		
	Height	2.6 mm Max		
	Width	0.87 in (22 mm)		
	Interface	ACS-3, SATA 3.2		
	Performance	Maximum Sequential Read	Maximum Sequential Write	
		3400 MB/s	2500 MB/s	
	Logical Blocks	1,000,215,216		
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]		
	Features	ATA Security; TCG Opal 2.0; FIPS DIPM; TRIM; DEVSLP		
		Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for system recovery software.		
1TB PCIe NVMe TLC M.2 2280 Solid State Drive	Form Factor	M.2 2280		
	Drive Weight	0.02 lb (10 g)		
	Capacity	1TB		
	NAND Type	TLC		
	Height	2.6 mm Max		
	Width	0.87 in (22 mm)		
	Interface	ACS-3, SATA 3.2		
	Performance	Maximum Sequential Read	Maximum Sequential Write	
		3480 MB/s	2800 MB/s	
		Logical Blocks	1,000,215,216	
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]		
	Features	ATA Security; TCG Opal 2.0; FIPS DIPM; TRIM; DEVSLP		
	Available in RAID 1 config	Yes		
		Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for system recovery software.		
2TB PCIe NVMe TLC M.2 2280 Solid State Drive	Form Factor	M.2 2280		
	Drive Weight	0.02 lb (10 g)		
	Capacity	2TB		
	NAND Type	TLC		
	Height	2.6 mm Max		

Technical Specifications – Storage

Width	0.87 in (22 mm)	
Interface	ACS-3, SATA 3.2	
Performance	Maximum Sequential Read	Maximum Sequential Write
	3180 MB/s	2920 MB/s
Logical Blocks	1,000,215,216	
Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]	
Features	ATA Security; TCG Opal 2.0; FIPS DIPM; TRIM; DEVSLP	
Available in RAID 1 config	Yes	

Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for system recovery software.

4TB PCIe NVMe TLC M.2 2280 Solid State Drive

Form Factor	M.2 2280	
Drive Weight	0.02 lb (10 g)	
Capacity	2TB	
NAND Type	TLC	
Height	2.6 mm Max	
Width	0.87 in (22 mm)	
Interface	ACS-3, SATA 3.2	
Performance	Maximum Sequential Read	Maximum Sequential Write
	530	400
Logical Blocks	1,000,215,216	
Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]	
Features	ATA Security; TCG Opal 2.0; FIPS DIPM; TRIM; DEVSLP	

Notes: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for system recovery software.

Optain available as out of cycle option
Can only be configured in Secondary Storage slot

500GB SATA 2.5" HDD

Form Factor	2.5"	
Drive Weight	0.02 lb (10 g)	
Capacity	500GB	
Generation	1100	
Height	2.6 mm Max	
Width	0.87 in (22 mm)	
Interface	ACS-3, SATA 3.2	
Performance	Maximum Sequential Read	Maximum Sequential Write
	530	400
Logical Blocks	1,000,215,216	
Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]	
Features	ATA Security; TCG Opal 2.0; FIPS DIPM; TRIM; DEVSLP	

Notes: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for system recovery software.

Technical Specifications – Storage

500GB SATA 2.5" SED HDD - FIPS-140-2

Form Factor	2.5"	
Drive Weight	0.02 lb (10 g)	
Capacity	500GB	
Generation	1100	
Height	2.6 mm Max	
Width	0.87 in (22 mm)	
Interface	ACS-3, SATA 3.2	
Performance	Maximum Sequential Read	Maximum Sequential Write
	530	400
Logical Blocks	1,000,215,216	
Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]	
Features	ATA Security; TCG Opal 2.0; FIPS DIPM; TRIM; DEVSLP	

Notes: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for system recovery software.

1TB SATA 2.5" HDD

Form Factor	2.5"	
Drive Weight	0.02 lb (10 g)	
Capacity	1TB	
Generation	1100	
Height	2.6 mm Max	
Width	0.87 in (22 mm)	
Interface	ACS-3, SATA 3.2	
Performance	Maximum Sequential Read	Maximum Sequential Write
	530	400
Logical Blocks	1,000,215,216	
Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]	
Features	ATA Security; TCG Opal 2.0; FIPS DIPM; TRIM; DEVSLP	

Notes: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for system recovery software.

2TB SATA 2.5" HDD

Form Factor	2.5"	
Drive Weight	0.02 lb (10 g)	
Capacity	2TB	
Generation	1100	
Height	2.6 mm Max	
Width	0.87 in (22 mm)	
Interface	ACS-3, SATA 3.2	
Performance	Maximum Sequential Read	Maximum Sequential Write
	530	400
Logical Blocks	1,000,215,216	
Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]	
Features	ATA Security; TCG Opal 2.0; FIPS DIPM; TRIM; DEVSLP	

Technical Specifications – Storage

Notes: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for system recovery software.

Technical Specifications – Networking

NETWORKING/COMMUNICATION

Intel i219LM 10/100/1000 Integrated NIC	Connector	RJ-45
	System Interface	PCI(Intel proprietary) + SMBus
	Data rates supported	10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14) 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30) 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40) Auto-Negotiation (Automatic Speed Selection) Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s
	IEEE Compliance	IEEE 802.1p QoS (Quality of Service) Support IEEE 802.1q VLAN support IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable) IEEE 802.3az EEE (Energy Efficient Ethernet)
	Performance	TCP/IP/UDP Checksum Offload (configurable) Protocol Offload (ARP & NS) Large send offload and Giant send offload Receiving Side Scaling Jumbo Frame 9K
	Power consumption	Cable Disconnection: 25mW 100Mbps Full Run: 450mW 1000bp Full Run: 1000mW WoL Enable(S3/S4/S5): 50mW WoL Disable(S3/S4/S5): 25mW
	Power Management	ACPI compliant – multiple power modes Situation-sensitive features reduce power consumption Advanced link down power saving for reducing link down power consumption
	Management Interface IT Manageability	Auto MDI/MDIX Crossover cable detection Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only) PXE 2.1 Remote Boot Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30)) Comprehensive diagnostic and configuration software suite Virtual Cable Doctor for Ethernet cable status
	Security & Manageability	Intel® vPro™ support with appropriate Intel® chipset components

Intel i219v 10/100/1000 Integrated NIC	Connector	RJ-45
	System Interface	PCI(Intel proprietary) + SMBus
	Data rates supported	10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14) 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30) 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40) Auto-Negotiation (Automatic Speed Selection) Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s
	IEEE Compliance	IEEE 802.1p QoS (Quality of Service) Support IEEE 802.1q VLAN support

Technical Specifications – Networking

Performance	<p>IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable)</p> <p>IEEE 802.3az EEE (Energy Efficient Ethernet)</p> <p>TCP/IP/UDP Checksum Offload (configurable)</p> <p>Protocol Offload (ARP & NS)</p> <p>Large send offload and Giant send offload</p> <p>Receiving Side Scaling</p> <p>Jumbo Frame 9K</p>
Power consumption	<p>Cable Disconnection: 25mW</p> <p>100Mbps Full Run: 450mW</p> <p>1000bp Full Run: 1000mW</p> <p>WoL Enable(S3/S4/S5): 50mW</p> <p>WoL Disable(S3/S4/S5): 25mW</p>
Power Management	<p>ACPI compliant – multiple power modes</p> <p>Situation-sensitive features reduce power consumption</p> <p>Advanced link down power saving for reducing link down power consumption</p>
Management Interface IT Manageability	<p>Auto MDI/MDIX Crossover cable detection</p> <p>Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only)</p> <p>PXE 2.1 Remote Boot</p> <p>Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30))</p> <p>Comprehensive diagnostic and configuration software suite</p> <p>Virtual Cable Doctor for Ethernet cable status</p>

NFC (Near Field Communication) module (optional)

Dimensions (L x W x H)	Module 50 mm by 23 mm by 2.89 mm
Chipset	SiM3U156+SiM3U154+AMS3911
System interface	USB 2.0
System interface (I/O)	Audio signal output on card read
NFC RF standards (In reading CSN)	<p>ISO/IEC 14443 A</p> <p>ISO/IEC 14443 B</p> <p>ISO/IEC 15693</p> <p>ISO/IEC 18092</p> <p>ECMA-340 NFCIP-1</p>
NFC Forum Support Reader Mode	<p>Tag Type 1, Type 2, Type3 and Type 4 in reading CSN</p> <p>13.56MHz:</p> <p>ISO/IEC 14443 A</p> <p>ISO/IEC 14443 B</p> <p>ISO/IEC 15693</p> <p>MIFARE 1K</p> <p>MIFARE 4K</p> <p>MIFARE DESFire</p> <p>FeliCa</p> <p>Topaz cards</p> <p>HID iClass ISO</p> <p>125kHz:</p> <p>HID Prox UID</p> <p>AWID UID</p>

Technical Specifications – Networking

		CASI-RUSCO UID
		EM 410x UID
		Indiana ASP/ASP+ UID
Frequency		13.56MHz and 125kHz
NFC Modes Supported		Reader
Raw RF Data Rates		106, 212 kbps
Operating temperature		-30°C to 70°C
Storage temperature		-40°C to 80°C
Humidity		10-90% operating 5-95% non-operating
Supply Operating voltage		4.35 to 5.25 Volts
Power Consumption	Mode	Power Consumption, Typical
	Polling	75mA
	Communication	85mA
Antenna		13.56MHz/125kHz combo antenna. Antenna connector, 0.5mm pitch, 16pin connector FPC.
Intel Wi-Fi 6 AX201 + BT5 (802.11ax 2x2, non-vPro, supporting gigabit file transfer speeds) non-vPro	Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac IEEE 802.11ax IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11i IEEE 802.11k IEEE 802.11r IEEE 802.11v
	Interoperability	Wi-Fi certified
	Frequency Band	802.11b/g/n/ax • 2.402 – 2.482 GHz 802.11a/n/ac/ax • 4.9 – 4.95 GHz (Japan) • 5.15 – 5.25 GHz • 5.25 – 5.35 GHz • 5.47 – 5.725 GHz • 5.825 – 5.850 GHz
	Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps • 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) • 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz) • 802.11ax : MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz)

Technical Specifications – Networking

Modulation	Direct Sequence Spread Spectrum OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM , 1024QAM
Security¹	<ul style="list-style-type: none"> • IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only • AES-CCMP: 128 bit in hardware • 802.1x authentication • WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. • WPA2 certification • IEEE 802.11i • WAPI
Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)
Roaming	IEEE 802.11 compliant roaming between access points
Output Power²	<ul style="list-style-type: none"> • 802.11b : +18.5dBm minimum • 802.11g : +17.5dBm minimum • 802.11a : +18.5dBm minimum • 802.11n HT20(2.4GHz) : +15.5dBm minimum • 802.11n HT40(2.4GHz) : +14.5dBm minimum • 802.11n HT20(5GHz) : +15.5dBm minimum • 802.11n HT40(5GHz) : +14.5dBm minimum • 802.11ac VHT80(5GHz) : +11.5dBm minimum • 802.11ac VHT160(5GHz) : +11.5dBm minimum • 802.11ax HT40(2.4GHz) : +10dBm minimum • 802.11ax VHT160(5GHz) : +10dBm minimum
Power Consumption	<ul style="list-style-type: none"> • Transmit mode 2.0 W • Receive mode 1.6 W • Idle mode (PSP) 180 mW (WLAN Associated) • Idle mode 50 mW (WLAN unassociated) • Connected Standby 10mW • Radio disabled 8 mW
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode
Receiver Sensitivity³	<ul style="list-style-type: none"> • 802.11b, 1Mbps : -93.5dBm maximum • 802.11b, 11Mbps : -84dBm maximum • 802.11a/g, 6Mbps : -86dBm maximum • 802.11a/g, 54Mbps : -72dBm maximum • 802.11n, MCS07 : -67dBm maximum • 802.11n, MCS15 : -64dBm maximum • 802.11ac, MCS0 : -84dBm maximum • 802.11ac, MCS9 : -59dBm maximum • 802.11ax, MCS11(HT40): -59dBm maximum • 802.11ax, MCS11(VHT160): -58.5dBm maximum
Antenna Type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications
Form Factor	PCI-Express M.2 MiniCard with CNVi Interface
Dimensions	<ol style="list-style-type: none"> 1. Type 2230 : 2.3 x 22.0 x 30.0 mm 2. Type 1216: 1.67 x 12.0 x 16.0 mm

Technical Specifications – Networking

Weight	1. Type 2230 : 2.8g 2. Type 126: 1.3g
Operating Voltage	3.3v +/- 9%
Temperature	Operating 14° to 158° F (-10° to 70° C) Non-operating -40° to 176° F (-40° to 80° C)
Humidity	Operating 10% to 90% (non-condensing) Non-operating 5% to 95% (non-condensing)
Altitude	Operating Non- 0 to 10,000 ft (3,048 m) operating 0 to 50,000 ft (15,240 m)
LED Activity	LED Amber – Radio Off; LED Off – Radio ON
HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0/5.1 Wireless Technology	
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy : 0~79 (1 MHz/CH) BLE : 0~39 (2 MHz/CH)
Data Rates and Throughput	Legacy : 3 Mbps data rate; throughput up to 2.17 Mbps BLE : 1 Mbps data rate; throughput up to 0.2 Mbps Legacy : Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy : Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 9.5 dBm for BR and EDR.
Power Consumption	Peak (Tx): 330 mW Peak (Rx): 230 mW Selective Suspend: 17 mW
Bluetooth Software Supported Link Topology	Microsoft Windows Bluetooth Software
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)

Technical Specifications – Networking

<p>Intel Wi-Fi 6 AX201 + BT5 (802.11ax 2x2, vPro, supporting gigabit file transfer speeds) vPro</p>	<p>Wireless LAN Standards</p>	<p>IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac IEEE 802.11ax IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11i IEEE 802.11k IEEE 802.11r IEEE 802.11v</p>
	<p>Interoperability</p>	<p>Wi-Fi certified</p>
	<p>Frequency Band</p>	<p>802.11b/g/n/ax • 2.402 – 2.482 GHz 802.11a/n/ac/ax • 4.9 – 4.95 GHz (Japan) • 5.15 – 5.25 GHz • 5.25 – 5.35 GHz • 5.47 – 5.725 GHz • 5.825 – 5.850 GHz</p>
	<p>Data Rates</p>	<p>• 802.11b: 1, 2, 5.5, 11 Mbps • 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) • 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz) • 802.11ax : MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz)</p>
	<p>Modulation</p>	<p>Direct Sequence Spread Spectrum OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM , 1024QAM</p>
	<p>Security¹</p>	<p>• IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only • AES-CCMP: 128 bit in hardware • 802.1x authentication • WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. • WPA2 certification • IEEE 802.11i • WAPI</p>
	<p>Network Architecture Models</p>	<p>Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)</p>
	<p>Roaming</p>	<p>IEEE 802.11 compliant roaming between access points</p>
	<p>Output Power²</p>	<p>• 802.11b : +18.5dBm minimum • 802.11g : +17.5dBm minimum • 802.11a : +18.5dBm minimum • 802.11n HT20(2.4GHz) : +15.5dBm minimum • 802.11n HT40(2.4GHz) : +14.5dBm minimum • 802.11n HT20(5GHz) : +15.5dBm minimum • 802.11n HT40(5GHz) : +14.5dBm minimum</p>

Technical Specifications – Networking

	<ul style="list-style-type: none"> • 802.11ac VHT80(5GHz) : +11.5dBm minimum • 802.11ac VHT160(5GHz) : +11.5dBm minimum • 802.11ax HT40(2.4GHz) : +10dBm minimum • 802.11ax VHT160(5GHz) : +10dBm minimum 				
Power Consumption	<ul style="list-style-type: none"> • Transmit mode :2.0 W • Receive mode :1.6 W • Idle mode (PSP) 180 mW (WLAN Associated) • Idle mode :50 mW (WLAN unassociated) • Connected Standby/Modern Standby: 10mW • Radio disabled: 8 mW 				
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode				
Receiver Sensitivity³	<ul style="list-style-type: none"> •802.11b, 1Mbps : -93.5dBm maximum •802.11b, 11Mbps : -84dBm maximum • 802.11a/g, 6Mbps : -86dBm maximum • 802.11a/g, 54Mbps : -72dBm maximum • 802.11n, MCS07 : -67dBm maximum • 802.11n, MCS15 : -64dBm maximum • 802.11ac, MCS0 : -84dBm maximum • 802.11ac, MCS9 : -59dBm maximum •802.11ax, MCS11(HT40): -59dBm maximum •802.11ax, MCS11(VHT160): -58.5dBm maximum 				
Antenna Type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications				
Form Factor	PCI-Express M.2 MiniCard with CNVi Interface				
Dimensions	<ol style="list-style-type: none"> 1. Type 2230 : 2.3 x 22.0 x 30.0 mm 2. Type 1216: 1.67 x 12.0 x 16.0 mm 				
Weight	<ol style="list-style-type: none"> 1. Type 2230 : 2.8g 2. Type 126: 1.3g 				
Operating Voltage	3.3v +/- 9%				
Temperature	<table border="0"> <tbody> <tr> <td>Operating</td> <td>14° to 158° F (-10° to 70° C)</td> </tr> <tr> <td>Non-operating</td> <td>-40° to 176° F (-40° to 80° C)</td> </tr> </tbody> </table>	Operating	14° to 158° F (-10° to 70° C)	Non-operating	-40° to 176° F (-40° to 80° C)
Operating	14° to 158° F (-10° to 70° C)				
Non-operating	-40° to 176° F (-40° to 80° C)				
Humidity	<table border="0"> <tbody> <tr> <td>Operating</td> <td>10% to 90% (non-condensing)</td> </tr> <tr> <td>Non-operating</td> <td>5% to 95% (non-condensing)</td> </tr> </tbody> </table>	Operating	10% to 90% (non-condensing)	Non-operating	5% to 95% (non-condensing)
Operating	10% to 90% (non-condensing)				
Non-operating	5% to 95% (non-condensing)				
Altitude	<table border="0"> <tbody> <tr> <td>Operating</td> <td>0 to 10,000 ft (3,048 m)</td> </tr> <tr> <td>Non-operating</td> <td>0 to 50,000 ft (15,240 m)</td> </tr> </tbody> </table>	Operating	0 to 10,000 ft (3,048 m)	Non-operating	0 to 50,000 ft (15,240 m)
Operating	0 to 10,000 ft (3,048 m)				
Non-operating	0 to 50,000 ft (15,240 m)				
LED Activity	LED Amber – Radio OFF; LED White – Radio ON				
HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0/5.1 Wireless Technology					
Frequency Band	2402 to 2480 MHz				
Number of Available Channels	Legacy : 0~79 (1 MHz/CH) BLE : 0~39 (2 MHz/CH)				
Data Rates and Throughput	<p>Legacy : 3 Mbps data rate; throughput up to 2.17 Mbps</p> <p>BLE : 1 Mbps data rate; throughput up to 0.2 Mbps</p> <p>Legacy : Synchronous Connection Oriented links up to 3, 64 kbps, voice channels</p> <p>Legacy : Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)</p>				

Technical Specifications – Networking

Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 9.5 dBm for BR and EDR.
Power Consumption	Peak (Tx): 330 mW Peak (Rx): 230 mW Selective Suspend: 17 mW
Bluetooth Software Supported Link Topology	Microsoft Windows Bluetooth Software
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)
Security & Manageability	Intel® vPro™ support with appropriate Intel® chipset components

Intel® XMM™ 7360 LTE-Advanced CAT9 (Pandora)*

Technology/Operating bands	FDD LTE: 2100 (Band 1), 1900 (Band 2), 1800 (Band 3), 1700/2100 (Band 4), 850 (Band 5), 2600 (Band 7), 900 (Band 8), 1400 (Band 11), 700 (Band 12 lower), 700 (Band 13 upper), 700 (Band 17 lower), 850 (Band 18 lower), 850 (Band 19 upper), 800 (Band 20), 1400 (Band 21), 850 (Band 26), 700 (Band 28), 700 (Band 29 RX only), 2300 (Band 30), 1700/2100 (Band 66). TDD LTE: 2600 (Band 38), 1900 (Band 39), 2400 (Band 40), 2500 (Band 41). HSPA+: 2100 (Band 1), 1900 (Band 2), 1700/2100 (Band 4), 850 (Band 5), 900 (Band 8) MHz
Wireless protocol standards	3GPP Release 11 LTE Specification CAT.9, DL 60MHz BW throughput up to 450Mbps; UL 20MHz throughput up to 50Mbps WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification
GPS	Standalone, A-GPS (MS-A, MS-B)
GPS bands	1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz, Beidou 1561.098 MHz

Technical Specifications – Networking

Maximum data rates	LTE: 450 Mbps (Download), 50 Mbps (Upload) DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21Mbps (Download), 5.76 Mbps (Upload)
Maximum output power	LTE: 23 dBm HSPA+: 23.5 dBm
Maximum power consumption	LTE: 1,200 mA (peak); 900 mA (average) HSPA+: 1,100 mA (peak); 800 mA (average)
Form Factor	M.2, 3042-S3 Key B
Weight	5.8 g
Dimensions (Length x Width x Thickness)	42 x 30 x 2.3 mm

* Mobile Broadband is an optional feature and requires configuration at purchase. Connection requires wireless data service contract, network support, and is not available in all areas. Contact service provider to determine the coverage area and availability. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products or in all countries.

Near Field Communications Controller (optional)

Dimensions (L x W x H)	Module 25 mm by 10 mm by 2.0 mm
Chipset	NPC100
System interface	I2C
NFC RF standards	ISO/IEC 14443 A ISO/IEC 14443 B ISO/IEC 15693 ISO/IEC 18092 ECMA-340 NFCIP-1 Target and Initiator ECMA-320 NFCIP-2
NFC Forum Support	Tag Type 1, Type 2, Type3 and Type 4, NFCIP-1 and NFCIP-2
Reader (PCD-VCD) Mode(1)	ISO/IEC 14443 A ISO/IEC 14443 B ISO/IEC 15693 MIFARE 1K MIFARE 4K MIFARE DESFire FeliCa Jewel and Topaz cards
Card Emulation (PICC-VICC) Mode(1)	ISO/IEC 14443 A ISO/IEC 14443 B and B' MIFARE FeliCa
Frequency	13.56 MHz
NFC Modes Supported	Reader/Writer, Peer-to-Peer
Raw RF Data Rates	106, 212, 424, 848 kbps
Operating temperature	0°C to 70°C
Storage temperature	-20°C to 125°C
Humidity	10-90% operating 5-95% non-operating

Technical Specifications – Networking

Supply Operating voltage	4.35 to 5.25 Volts
I/O Voltage	1.8V or 3.3V
Power Consumption	Booster enable, VBAT= 3.3V, VCC_BOOST = 5V) Mode Power Consumption, Typical
	Polling 7.3 mA
	Detected Test Tag Type 1 Total 283.8 mA Net Module 236.8 mA
	Detected Test Tag Type 2 Total 288.8 mA Net Module 241.8 mA
	Detected Test Tag Type 3 Total 287.7 mA Net Module 240.7 mA
	Detected Test Tag Type 4 Total 282.3 mA Net Module 235.3 mA
Antenna	Antenna connector, 0.5mm pitch, 7 connector FPC. Antenna matching is external to module.

Technical Specifications – Power

POWER

120 Watt Slim Smart AC Adapter	Dimensions	138x68.5x25.4mm	
	Weight	unit: 350g +/- 10g	
	Input	Input Efficiency	88% at 115 Vac and 89% at 230Vac
		Input frequency range	47 ~ 63 Hz
		Input AC current	1.7 A at 90 Vac and Maximum Load
	Output	Output power	120W
		DC output	19.5V
		Hold-up time	5ms at 115 Vac input
		Output current limit	<18.0A
		Connector	C14
	Environmental Design	Operating temperature	32° to 95° F (0° to 35° C)
		Non-operating (storage) temperature	-4° to 185° F (-20° to 85° C)
		Altitude	0 to 16,400 ft (0 to 5,000 m)
		Humidity	5% to 95%
		Storage Humidity	5% to 95%
EMI and Safety Certifications	Eg: *CE Mark - full compliance with LVD and EMC directives * Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. * MTBF - over 200,000 hours at 25°C ambient condition.		

*Can only be configured with Intel UMA Graphics option

150 Watt Slim Smart AC Adapter	Dimensions	138x66x22mm	
	Weight	unit: 325g +/- 10g	
	Input	Input Efficiency	88% at 115 Vac and 89% at 230Vac
		Input frequency range	47 ~ 63 Hz
		Input AC current	2.7 A at 90 Vac and Maximum Load
	Output	Output power	150W
		DC output	19.5V
		Hold-up time	5ms at 115 Vac input
		Output current limit	<16.0A
		Connector	C14
Environmental Design	Operating temperature	32° to 95° F (0° to 35° C)	

Technical Specifications – Power

Non-operating (storage) temperature	-4° to 185° F (-20° to 85° C)
Altitude	0 to 16,400 ft (0 to 5000m)
Humidity	5% to 95%
Storage Humidity	5% to 95%

EMI and Safety Certifications

Eg:
 *CE Mark - full compliance with LVD and EMC directives
 * Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.
 * MTBF - over 200,000 hours at 25°C ambient condition.

*Can only be configured with Quadro T1000 and T2000 Graphics option

200 Watt UltraSlim Smart AC Adapter

Dimensions	152x73x23.5mm	
Weight	unit: 530g +/- 10g	
Input	Input Efficiency	88% at 115 Vac and 89% at 230Vac
	Input frequency range	47 ~ 63 Hz
	Input AC current	2.9 A at 90 Vac and Maximum Load
	Output	Output power
DC output		19.5V
Hold-up time		5ms at 115 Vac input
Output current limit		<16.0A
Connector	C14	
Environmental Design	Operating temperature	32° to 95° F (0° to 35° C)
	Non-operating (storage) temperature	-4° to 185° F (-20° to 85° C)
	Altitude	0 to 16,400 ft (0 to 5000m)
	Humidity	5% to 95%
	Storage Humidity	5% to 95%
EMI and Safety Certifications	Eg:	
	*CE Mark - full compliance with LVD and EMC directives	
	* Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.	
	* MTBF - over 100,000 hours at 25°C ambient condition.	

*Can only be configured with Quadro RTX3000, RTX4000, RTX5000 Graphics and Radeon W5500M, RX 5500M Graphics option

Technical Specifications – Power

HP Long Life 8-cell Polymer (94Wh) Battery	Cells/Type	8 cell
	Energy	Voltage 11.55V Amp-hour capacity 4.15Ah
	Temperature	Operating (Charging) 0° to 60° C Operating (Discharging) -20° to 70° C
	Fuel Gauge LED	NA
	Warranty	Depends on system offering
	Optional Travel Battery Available	No

* Batteries have a default one year limited warranty except for Long Life batteries which will have same 1-year or 3-year limited warranty as the platform.

Refer to <http://www.hp.com/support/batterywarranty/> for battery warranty information.

Technical Specifications – Environmental

ENVIRONMENTAL DATA

Eco-Label Certifications & declarations

This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:

- IT ECO declaration
- US ENERGY STAR®
- EPEAT® Gold registered in the United States. See <http://www.epeat.net> for registration status in your country.

System Configuration

The configuration used for the Energy Consumption and Declared Noise Emissions data for the Notebook model is based on a “Typically Configured Notebook”.

Energy Consumption (in accordance with US ENERGY STAR® test method)

	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz
Normal Operation (Short idle)	9.95 W	10.02 W	9.92 W
Normal Operation (Long idle)	6.08 W	6.21 W	6.06 W
Sleep	1.61 W	1.68 W	1.54 W
Off	0.437 W	0.46 W	0.40 W

NOTE:

Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.

Heat Dissipation*

	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz
Normal Operation (Short idle)	34.03 BTU/hr	34.27 BTU/hr	33.93 BTU/hr
Normal Operation (Long idle)	20.79 BTU/hr	21.24 BTU/hr	20.73 BTU/hr
Sleep	5.51 BTU/hr	5.75 BTU/hr	5.27 BTU/hr
Off	1.49 BTU/hr	1.57 BTU/hr	1.37 BTU/hr

***NOTE:** Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.

Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)

	Sound Power (L_{WAd} , bels)	Sound Pressure (L_{pAm} , decibels)
Typically Configured – Idle	2.6	16
Fixed Disk – Random writes	3.7	22
Optical Drive – Sequential reads	2.9	17.4

Longevity and Upgrading

"This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include:

- AC Adapter
- Battery
- WLAN/WWAN module
- 4 storage slots (M.2 and HDD)
- 4 SODIMM memory slots

Technical Specifications – Environmental

Spare parts are available throughout the warranty period and or for up to “5” years after the end of production.

Batteries

This battery(s) in this product comply with EU Directive 2006/66/EC

Batteries used in the product do not contain:

Mercury greater than 1ppm by weight

Cadmium greater than 20ppm by weight

Battery description: CR2032 (coin cell)

Battery type: Lithium

Battery description: 8 cell HP Long Life Polymer 94Wh (4.15Ah)

Additional Information

- This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC.
- This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC.
- This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986).
- This product is in compliance with the IEEE 1680 (EPEAT) standard at the Gold level, see www.epeat.net
- Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043.
- This product contains 10.08% post-consumer recycled plastic (by wt.)
- This product is 94.2% recycle-able when properly disposed of at end of life.

Packaging Materials

External:	PAPER/Corrugated	0.375 g
	PAPER/Molded Pulp	0.202 g
Internal:	PLASTIC/Polyethylene low density - LDPE	0.012 g
	PLASTIC/Polypropylene - PP	0.005 g

The plastic packaging material contains at least 50% recycled content.

The corrugated paper packaging materials contains at least 12.6 recycled content.

RoHS Compliance

HP Inc. complies fully with materials regulations. We were among the first companies to extend the restrictions in the European Union (EU) Restriction of Hazardous Substances (RoHS) Directive to our products worldwide through the HP GSE. HP has contributed to the development of related legislation in Europe, as well as China, India, and Vietnam.

We believe the RoHS directive and similar laws play an important role in promoting industry-wide elimination of substances of concern. We have supported the inclusion of additional substances—including PVC, BFRs, and certain phthalates—in future RoHS legislation that pertains to electrical and electronics products.

We met our voluntary objective to achieve worldwide compliance with the new EU RoHS requirements for virtually all relevant products by July 2013, and we will continue to extend the scope of the commitment to include further restricted substances as regulations continue to evolve.

To obtain a copy of the HP RoHS Compliance Statement, see [HP RoHS position statement](#).

Technical Specifications – Environmental

Material Usage

This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/supplychain/gen_specifications.html):

- Asbestos
- Certain Azo Colorants
- Certain Brominated Flame Retardants – may not be used as flame retardants in plastics
- Cadmium
- Chlorinated Hydrocarbons
- Chlorinated Paraffins
- Bis(2-Ethylhexyl) phthalate (DEHP)
- Benzyl butyl phthalate (BBP)
- Dibutyl phthalate (DBP)
- Diisobutyl phthalate (DIBP)
- Formaldehyde
- Halogenated Diphenyl Methanes
- Lead carbonates and sulfates
- Lead and Lead compounds
- Mercuric Oxide Batteries
- Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user.
- Ozone Depleting Substances
- Polybrominated Biphenyls (PBBs)
- Polybrominated Biphenyl Ethers (PBBEs)
- Polybrominated Biphenyl Oxides (PBBOs)
- Polychlorinated Biphenyl (PCB)
- Polychlorinated Terphenyls (PCT)
- Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been voluntarily removed from most applications.
- Radioactive Substances
- Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)

Packaging Usage

HP follows these guidelines to decrease the environmental impact of product packaging:

- Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.
- Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
- Design packaging materials for ease of disassembly.
- Maximize the use of post-consumer recycled content materials in packaging materials.
- Use readily recyclable packaging materials such as paper and corrugated materials.
- Reduce size and weight of packages to improve transportation fuel efficiency.
- Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.

End-of-life Management and Recycling

Hewlett-Packard offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: <http://www.hp.com/go/reuse-recycle> or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.

The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: <http://www.hp.com/go/recyclers>.

Technical Specifications – Environmental

These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.

HP Inc. Corporate Environmental Information

For more information about HP's commitment to the environment:

Global Citizenship Report

<http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html>

Eco-label certifications

<http://www8.hp.com/us/en/hp-information/environment/ecolabels.html>

ISO 14001 certificates:

<http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842>

and

<http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf>

Options and Accessories (sold separately and availability may vary by country)

Type	Description	Part #
Displays	HP Z32 31.5" 4k UHD Display	1AA81A8#XXX
	HP Z38c 37.5" Curved Display	Z4W65A8#XXX
Case	HP Business Backpack (up to 17.3")	2SC67AA
	HP Business Slim Top Load (up to 17.3")	2UW02AA
	HP Exec 17.3 Midnight Backpack	1KM17AA
Docking Accessories	HP Adjustable Dual Monitor Stand	AW664AA
	HP Adjustable Display Stand	AW663AA
	HP Display and Notebook Stand II	E8G00AA
	HP Monitor Stand	M9X76AA
	HP Dual Hinge II Notebook Stand	E8F99AA
	HP Hot Desk Stand (up to 32" monitor)	W3Z73AA
	HP Hot Desk Stand Monitor Arm (for use with W3Z73AA; supports two 24" monitors)	W3Z74AA
	HP TB Audio Module (comp with Hook dock)	3AQ21AA
Docking station	HP TB Dock G2 Combo Cable (this is 230W) comp with Hook dock	3XB96AA
	HP USB-C Mini Dock - power not supported on mWKS	1PM64AA
	HP TB Dock G2 w/ Combo Cable (this is 230W)	3TR87AA
	HP USB-C/A Universal Dock G2 Power Not Supported on Mobile Workstations	5TW13AA
Input/Output - Mice	HP USB-C Dock G5 Power Not Supported on Mobile Workstations	5TW10AA
	HP Comfort Grip Wireless Mouse (See Link 5 Tab)	H2L63AA
	HP 3-button USB Laser Mouse	H4B81AA
	HP Bluetooth Travel Mouse	6SP30AA
	HP USB Travel Mouse	G1K28AA
	HP Wireless Premium Mouse (See Link 5 Tab)	1JR31AA
Input/Output - Keyboard	HP Elite Presenter Mouse	2CE30AA
	HP Slim USB Keyboard and Mouse	T6T83AA
Input/Output - Adapter	HP Slim Wireless Keyboard and Mouse	T6L04AA
	HP USB-C to USB-A Hub	Z6A00AA
	HDMI to VGA Adapter	H4F02AA
	HP HDMI to DVI Adapter	F5A28AA
	HP USB-C to USB 3.0 Adapter	N2Z63AA
	HP USB-C to DisplayPort Adapter	N9K78AA
	HP USB-C to VGA Adapter	N9K76AA
HP Single miniDP-to-DP Adapter Cable	2MY05AA	
Collaboration	HP UC Wired Headset	K7V17AA

Options and Accessories (sold separately and availability may vary by country)

Memory	HP 8GB 2666Mhz DDR4	4VN06AA
	HP 16GB 2666Mhz DDR4	4VN07AA
	HP 32GB 2666MHz DDR4	6NX83AA
	HP 8GB 2666MHz DDR4 ECC	4UY11AA
	HP 16GB 2666MHz DDR4 ECC	4UY12AA
Power - A/C Adapter	HP 200W Smart AC Adapter (4.5mm)	
	HP 200W Smart AC Adapter (4.5mm)	
Adapter Dongle	HP 7.4mm to 4.5mm DC Dongle	KOQ39AA
Security	HP Essential Combination Lock	TOY16AA
	HP Keyed Cable Lock 10mm	T1A62AA
	HP Dual Head Keyed Cable Lock	T1A64AA
Storage - External	HP External USB DVDRW Drive	F2B56AA
Storage - SS M2	HP 256GB PCIe 3x4 NVMe SSD (2280)	V3K66AA
	HP 512GB PCIe 3x4 NVMe DS SSD (2280)	V3K67AA

Copyright © 2020 HP Development Company, L.P. The information contained herein is subject to change without notice. The only warranties for HP products are set forth in the express limited warranty statements accompanying such products. Nothing herein should be construed as constituting an additional warranty. HP shall not be liable for technical or editorial errors or omissions contained herein.

Intel, Core, and Celeron, Thunderbolt and vPro are registered trademarks or trademarks of Intel Corporation or its subsidiaries in the U.S. and/or other countries. Bluetooth is a registered trademark of its proprietor used by HP Inc. under license. AMD, FirePro, and Enduro are trademarks of Advanced Micro Devices, Inc. Adobe is a trademark of Adobe Systems Incorporated. Microsoft and Windows are U.S. registered trademarks of Microsoft Corporation in the United States and/or other countries. Qualcomm and Snapdragon are trademarks of Qualcomm, Inc. SD, SDHC, and SDXC are trademarks or registered trademarks of SD-3C in the United States, other countries or both. USB Type-C and USB-C are trademarks of USB Implementers Forum. ENERGY STAR® is a registered trademark mark of the U.S. Environmental Protection Agency.

Date of change:	Version History:		Description of change:
September 11, 2020	From v1 to v2	Changed	Format
September 30, 2020	From v2 to v3	Changed	At A Glance, GRAPHICS, STORAGE AND DRIVES, SOFTWARE AND SECURITY, NETWORKING/COMMUNICATION, ENVIRONMENTAL DATA and Options and Accessories sections
October 20, 2020	From v3 to v4	Changed	Format
November 20, 2020	From v4 to v5	Changed	Format